



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

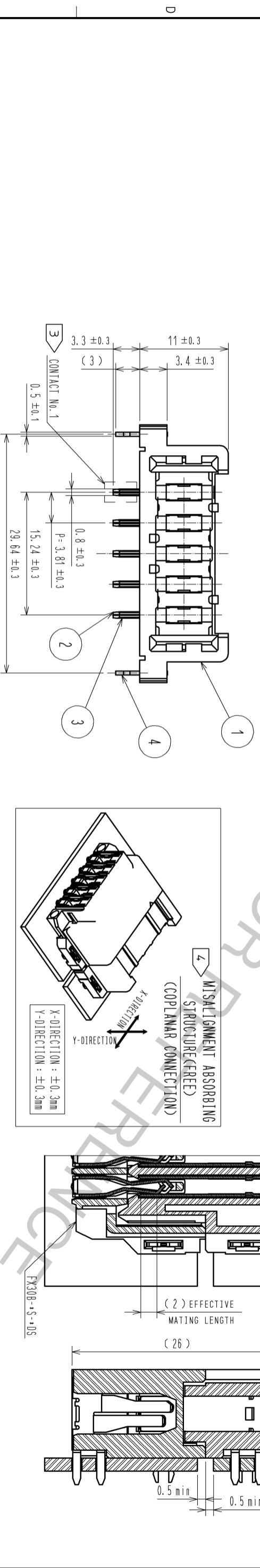
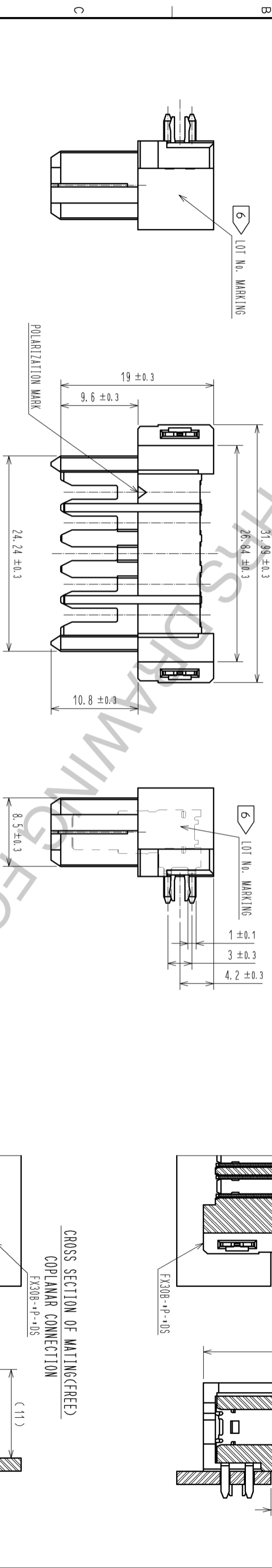
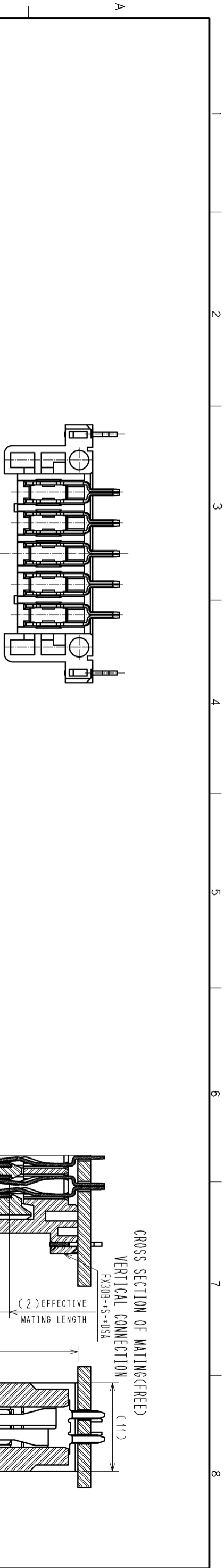
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FORM HCO011-5-7-AN 1 2 3 4 5 6 7 8



- NOTE
- THIS PRODUCT IS PACKAGED IN TRAY. (20PCS/TRAY)
 - BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN'T AFFECT QUALITY LEVEL.
ALSO, BLACK SPOT COULD BE OBSERVED ON THE SURFACE OF HOUSING.
 - FOR THE CONTACT NO., ADJACENT TWO PAIRS OF LEADS PLACED BACK-TO-BACK (4 LEADS IN TOTAL) COMPOSE ONE LINE.
 - MISALIGNMENT ABSORBING RANGE: ± 0.3 mm max.
 - THE DIMENSION IN PARENTHESES ARE FOR REFERENCES.
 - LOT NO. IS INDICATED AT EITHER ONE OF THE POSITION AS SHOWN.
 - PAY ATTENTION TO THE RECOMMENDED PCB THICKNESS AND FINISHED THROUGH-HOLE DIMENSIONS. LOW RETENTION FORCE TO PCB COULD INDUCE ANGLED MOUNTING DUE TO THE UNBALANCED CENTER OF THE CONNECTOR.

NO. 1	POLYAMIDE	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
2	COPPER ALLOY	CONTACT AREA: GOLD-PLATING 0.1 μ m LEAD AREA: TIN-PLATING 1.0 μ m UNDER PLATING: NICKEL 1.0 μ m	4	PHOSPHOR BRONZE	TIN-PLATING 3.0 μ m UNDER PLATING: NICKEL 1.0 μ m
3	COPPER ALLOY	CONTACT AREA: GOLD-PLATING 0.1 μ m LEAD AREA: TIN-PLATING 1.0 μ m UNDER PLATING: NICKEL 1.0 μ m	5	POLYSTYRENE	

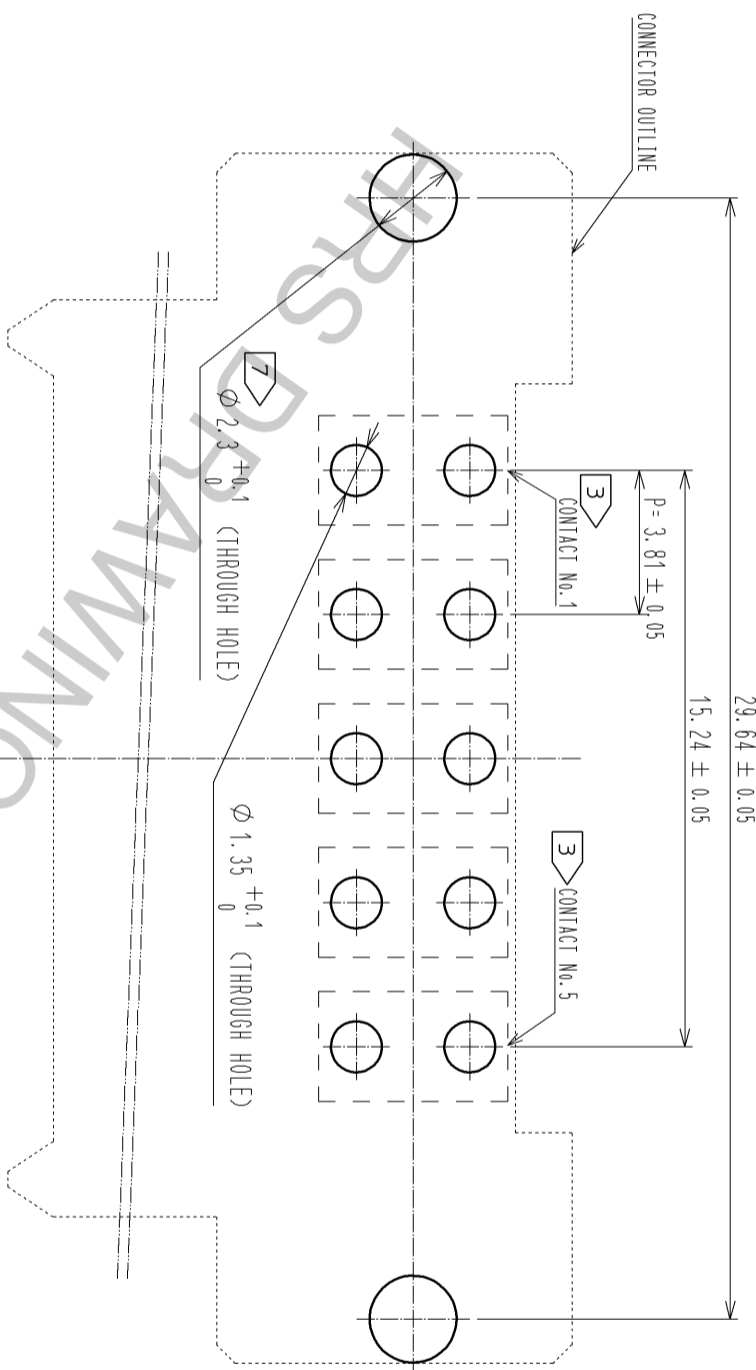
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1					

APPROVED	HS. OKAWA	13.03.13	DRAWING NO.	EDC3-347271-00
CHECKED	KI. HIROKAWA	13.03.12	PART NO.	FX30B-5P-3.81DS
DESIGNED	DK. AIMOTO	13.03.11	CODE NO.	CL570-3403-5-00
DRAWN	DK. AIMOTO	13.03.11		

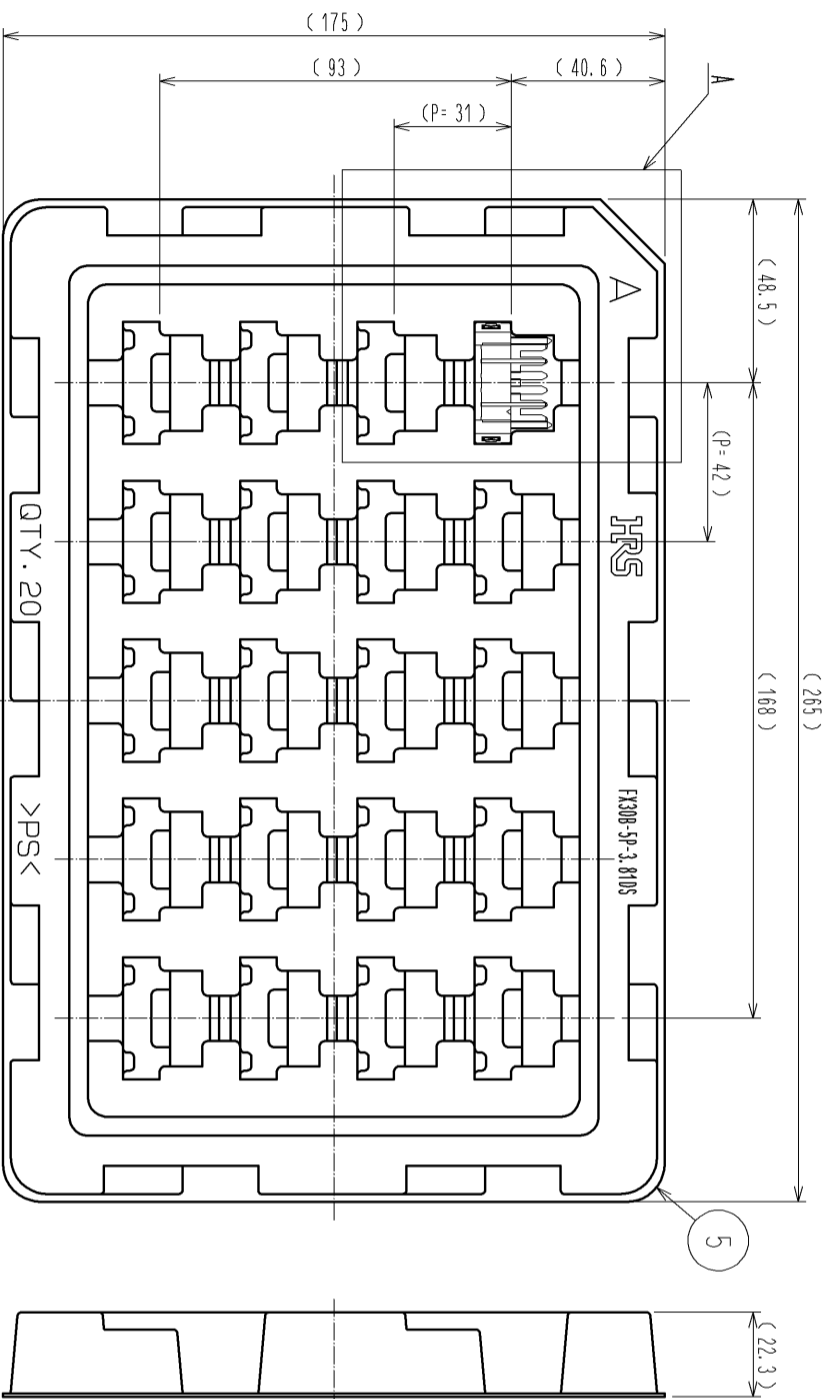


HIROSE ELECTRIC CO., LTD.

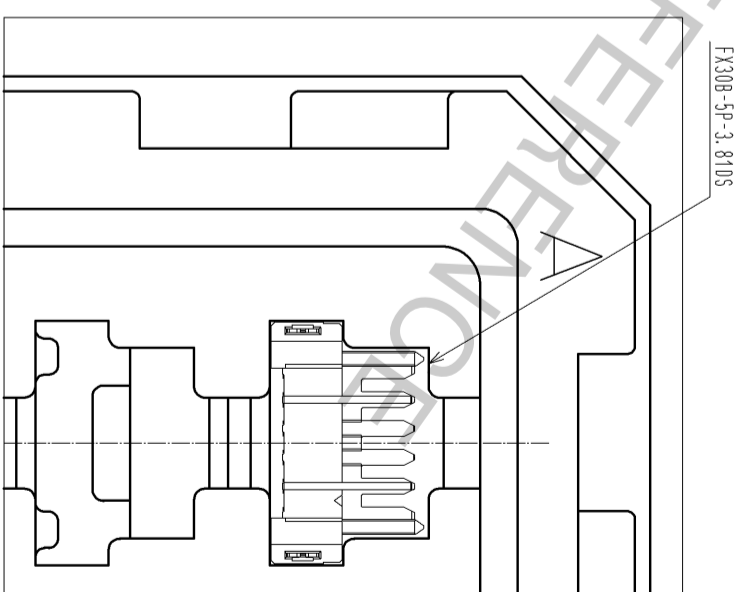
RECOMMENDED HOLE PATTERN DIMENSION OF PCB(5:1)
 (CONNECTOR MOUNTING SIDE, PCB THICKNESS: t=1.6mm) 7



1 DRAWING FOR PACKAGING(1:2)



A(1:1)



HR5	
DRAWING NO.	EDC3-347271-00
PART NO.	FX30B-5P-3.81DS
CODE NO.	CL570-3403-5-00
	2/2